

CLAIMS

1. A method of repairing a pedestal surface, comprising the step of polishing said surface using a coarse surface of a film.  
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2. A method according to claim 1, wherein the film has a coarseness of from 1 to 45 microns.
3. A method of repairing a pedestal surface, comprising the step of polishing said surface using a coarse surface with a coarseness of from 1 to 45 microns.  
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4. A method according to claim 3, wherein the coarse surface is a coarse surface of a film.
- 15 5. A method according to any one to claims 1, 2 and 4, wherein the film is mounted on one side of a silicon wafer.
6. A method according to claim 5, wherein the film is mounted on the silicon wafer using a mineral oil as an adhesive.  
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7. A method according to claim 6, wherein the mineral oil is a fluorinated oil
8. A method according to any one of claims 5 to 7, wherein the other side of the silicon wafer from the coarse surface has tape thereon to provide an improved grip.  
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9. A method according to any one to preceding claims, further comprising the step of applying IPA between the coarse surface and the pedestal surface prior to polishing.  
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10. A method according to any one to preceding claims, wherein the coarse surface comprises diamond grains.

11. A method according to any one to preceding claims, wherein the pedestal is a heater pedestal.
- 5 12. A method according to any one to preceding claims, wherein the pedestal is a pedestal for use in CVD, PVD, metal / oxide etching, photolithographic scanning or semiconductor processing that requires heating or a vacuum or mechanical devices to secure the position of a wafer to the pedestal surface.
- 10 13. A pedestal repaired according to the method of any one of the preceding claims.
14. A pedestal repair apparatus comprising a silicon wafer, with a coarse film on one side thereof.